

View Online at <https://aerobasegroup.com/nsn/5910-01-330-2335>

**Body Style:**

Chip type

**Reliability Indicator:**

Established

**Reliability Failure Rate Level In Percent:**

0.001

**Terminal Length:**

Between 0.3 millimeters and 0.7 millimeters

**Body Length:**

2.0 millimeters

**Body Width:**

1.3 millimeters

**Body Height:**

1.3 millimeters

**Schematic Diagram Designator:**

No common or grounded electrode (s)

**Insulation Resistance At Maximum Operating Temp:**

10000.0 megohms

**Capacitance Value Per Section:**

18.000 picofarads single section

**Nonderated Operating Temp:**

Between -55.0 degrees celsius and 125.0 degrees celsius

**Temperature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius:**

0.0 single section

**Nonderated Continuous Voltage Rating And Type Per Section:**

100.0 dc single section

**Tolerance Of Temperature Coefficient Per Section In Ppm Per Deg Celsius:**

-30.0/+30.0 single section

**Tolerance Range Per Section:**

-1.00/+1.00 percent single section

**Case Material:**

Ceramic

**Insulation Resistance At Reference Temp:**

100000.0 megohms

**Dissipation Factor At Reference Temperature In Percent:**

0.150

**Terminal Surface Treatment:**

Solder

**Test Data Document:**

81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).

**Terminal Type And Quantity:**

2 bonding pad

**Specification Data:**

81349-mil-c-55681/7 government specification

**Shelf Life:**

N/a

**Unit Of Measure:**

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**Demilitarization:**

No

**Fiig:**

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